

2SC3380

Silicon NPN Triple Diffused

REJ03G0713-0300 (Previous ADE-208-1082A) Rev.3.00 Aug.10.2005

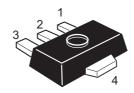
Application

- High frequency high voltage amplifier
- High voltage switch

Outline

RENESAS Package code: PLZZ0004CA-A

(Package name: UPAK®)



1. Base

2. Collector

3. Emitter

4. Collector (Flange)

Note: Marking is "AS".

*UPAK is a trademark of Renesas Technology Corp.

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	300	V
Collector to emitter voltage	V _{CEO}	300	V
Emitter to base voltage	V _{EBO}	5	V
Collector current	I _C	100	mA
Collector power dissipation	Pc*1	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

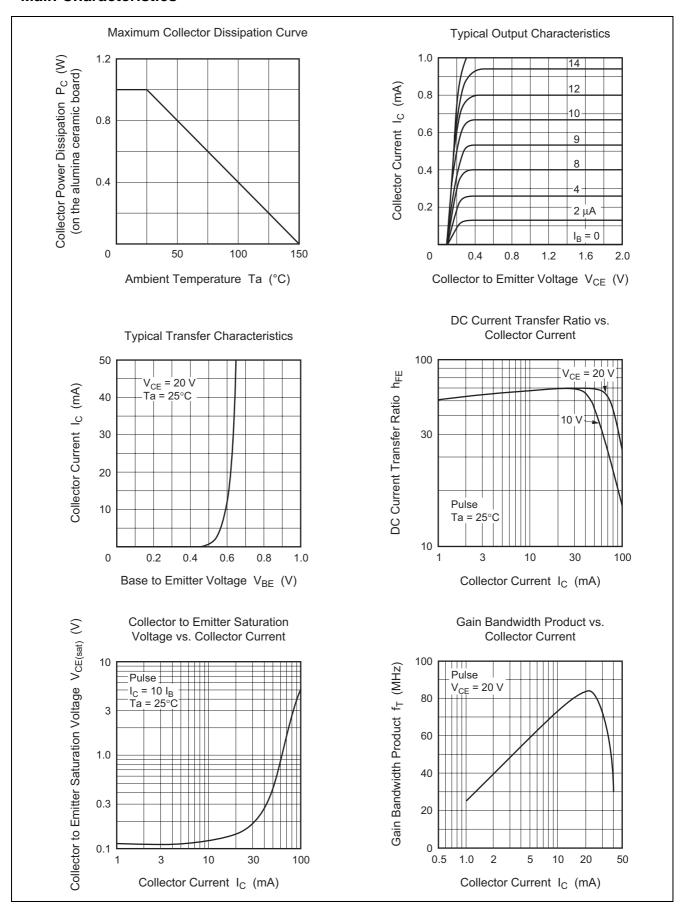
Note: 1. Value on the alumina ceramic board $(12.5 \times 20 \times 0.7 \text{ mm})$

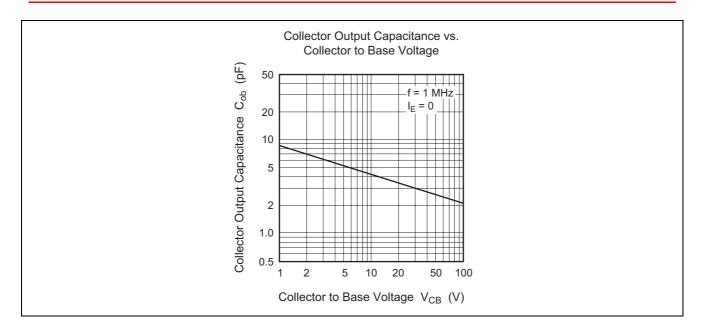
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

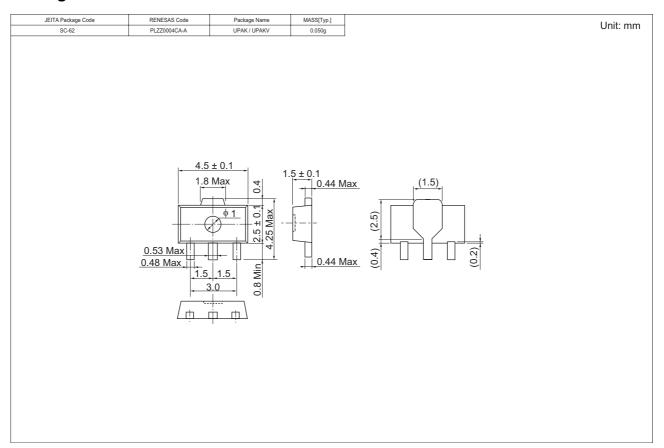
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	300	_	_	V	$I_C = 10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	300	_	_	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_E = 10 \mu\text{A}, I_C = 0$
Collector cutoff current	I _{CEO}	_	_	1	μΑ	V _{CE} = 250 V, R _{BE} = ∞
Collector to emitter saturation voltage	V _{CE(sat)}	_	_	1.5	V	$I_C = 20 \text{ mA}, I_B = 2 \text{ mA}$
DC current transfer ratio	h _{FE}	30	_	200		$V_{CE} = 20 \text{ V}, I_{C} = 20 \text{ mA}$
Gain bandwidth product	f⊤	_	80	_	MHz	$V_{CE} = 20 \text{ V}, I_{C} = 20 \text{ mA}$
Collector output capacitance	Cob	_	_	4	рF	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$

Main Characteristics





Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SC3380ASTR-E	1000	φ 178 mm Reel, 12 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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